

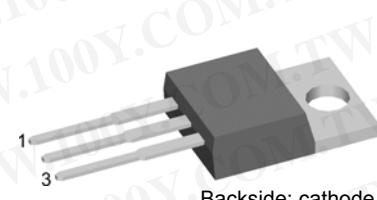
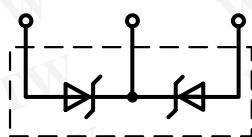
advanced

Schottky

High Performance Schottky Diode
 Low Loss and Soft Recovery
 Common Cathode

Part number

DSA 30 C 150PB



Backside: cathode

Features / Advantages:

- Very low V_f
- Extremely low switching losses
- Low I_{rm} -values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

Package:

TO-220AB

- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

勝特力材料 886-3-5753170
 胜特力电子(上海) 86-21-34970699
 胜特力电子(深圳) 86-755-83298787

[Http://www.100y.com.tw](http://www.100y.com.tw)

Ratings

Symbol	Definition	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ\text{C}$			150	V
I_R	reverse current	$V_R = 150\text{ V}$			0.5	mA
		$V_R = 150\text{ V}$			2.5	mA
V_F	forward voltage	$I_F = 15\text{ A}$			0.89	V
		$I_F = 30\text{ A}$			1.02	V
		$I_F = 15\text{ A}$			0.75	V
		$I_F = 30\text{ A}$			0.89	V
I_{FAV}	average forward current	rectangular, $d = 0.5$	$T_c = 150^\circ\text{C}$		15	A
V_{FO} r_F	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 175^\circ\text{C}$		0.55	V
					8.8	$\text{m}\Omega$
R_{thJC}	thermal resistance junction to case				1.75	K/W
T_{VJ}	virtual junction temperature		-55		175	$^\circ\text{C}$
P_{tot}	total power dissipation	$T_c = 25^\circ\text{C}$			85	W
I_{FSM}	max. forward surge current	$t_p = 10\text{ ms}$ (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$		120	A
C_J	junction capacitance	$V_R = \text{tbd V}; f = 1\text{ MHz}$	$T_{VJ} = 25^\circ\text{C}$	tbd		pF
E_{AS}	non-repetitive avalanche energy	$I_{AS} = 1\text{ A}; L = 100\text{ }\mu\text{H}$	$T_{VJ} = 25^\circ\text{C}$		0.05	mJ
I_{AR}	repetitive avalanche current	$V_A = 1.5 \cdot V_R$ typ.; $f = 10\text{ kHz}$			0.1	A

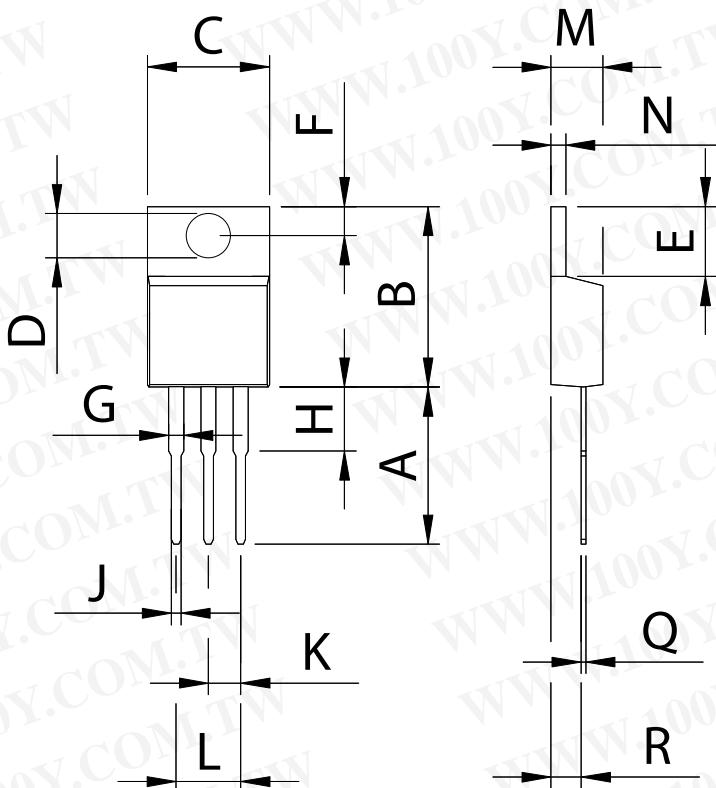
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Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
I_{RMS}	RMS current	per pin*			35	A
R_{thCH}	thermal resistance case to heatsink			0.50		K/W
M_D	mounting torque		0.4		0.6	Nm
F_C	mounting force with clip		20		60	N
T_{stg}	storage temperature		-55		150	°C
Weight				2		g

* I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

Outlines TO-220AB



Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	12.70	13.97	0.500	0.550
B	14.73	16.00	0.580	0.630
C	9.91	10.66	0.390	0.420
D	3.54	4.08	0.139	0.161
E	5.85	6.85	0.230	0.270
F	2.54	3.18	0.100	0.125
G	1.15	1.65	0.045	0.065
H	2.79	5.84	0.110	0.230
J	0.64	1.01	0.025	0.040
K	2.54	BSC	0.100	BSC
M	4.32	4.82	0.170	0.190
N	1.14	1.39	0.045	0.055
Q	0.35	0.56	0.014	0.022
R	2.29	2.79	0.090	0.110

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